AUTO EQUIPMENT

SOLUTION PROVIDER

萬潤科技

AllRing Tech

Stock Code:6187.TT

Disclaimer

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All prospects reflect Allring-tech expectations toward the future, and may be subject to change and Allring-tech reserves the right to alter, update and change relevant information from time to time without prior notice.

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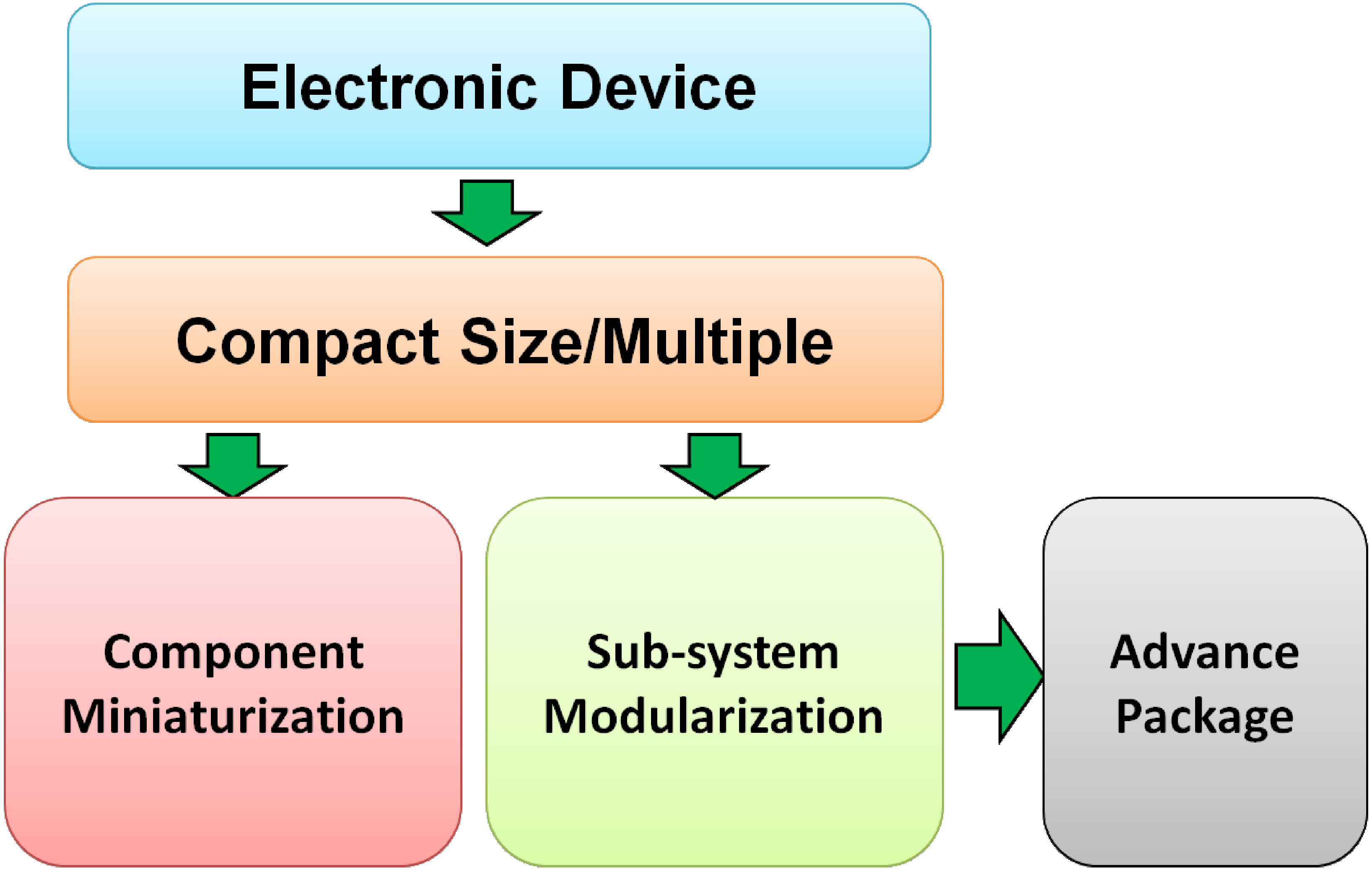
4 Future Prospects

Company Profile

Established	May 24, 1996
Capital	NTD 833 Million (USD 27 Million)
Business	Automation equipment supplier for Semiconductor test & package, Passive Component manufacturing industries
Employee	219 (Feb, 2020)
Chairman	Larry Lu
Address	No.1 Luke 10th Rd. ,Lujhu,Kaohsiung,Taiwan
Website	www.allring-tech.com.tw

Industry Overview



Electronic Device

Compact Size/Multiple

Component Miniaturization

Sub-system Modularization

Advance Package

Advance Package

Packaging Type		Manufacturer		Application
SIP (system in package)		OSAT	ASE	Smart phone IoT Mobile
			USI	
		Module house	Hon Hai	
			Pegatron	
		Component	AAC	
			Luxshare	
WLP (wafer level package)	InFO	Foundry	TSMC	Smart Phone
	CoWoS		TSMC	
Flip chip	2D/3D	OSAT	ASE	Smart Phone IoT Mobile
			Spil	
			Amkor	
			JCET	
			Powertech	

Customer Base

Semiconductor	Passive Component
tsmc	muRata
ASE GROUP	TAIYO YUDEN
SPIL	VISHAY
ChipMOS	KYOCERA
UTAC	YAGEO
WALTON	PSA
Amkor Technology	DARFON
ATC	TAI-TECH TAI-TECH Advanced Electronics Co., Ltd.
	CHILISIN
	SAMSUNG
	Sunlord EXPERT IN PASSIVE PARTS
	EYANG
	microgate

Product line up

Mounter Series of Semiconductor

- ◆ Optical Adhesion Attach
- ◆ PSA Attach
- ◆ FPC Mounter
- ◆ ACF Mounter

Why us?

- ✓ Customized Design for different size and shape products.
- ✓ Included In-House AOI and sensing control

Product line up

Dispenser Series

- ◆ Under Fill Dispenser (BGA/Wafer)
- ◆ Flux Jetting Dispenser
- ◆ Heat Sink Dispenser

In-House Pump type

- ◆ Jetting
- ◆ Auger
- ◆ Spray
- ◆ Air pulse

Type	**Jetting**
	RK-PIEZO 3000
	
Dispensing Method	Piezo-electric
Fluid Viscosity range, mPa.s (reference)	10 ~ 80,000
Operation Cycle, dps	Max. 1000
Dot Weight, mg/dot	0.002~0.1
Dispensing Precision	1mg±5% C_{PK}>1.66

Product line up

AOI Series of Semiconductor

- ◆Die Bonding AOI
- ◆6 surface Inspection
- ◆Wafer UF Inspection

Product line up

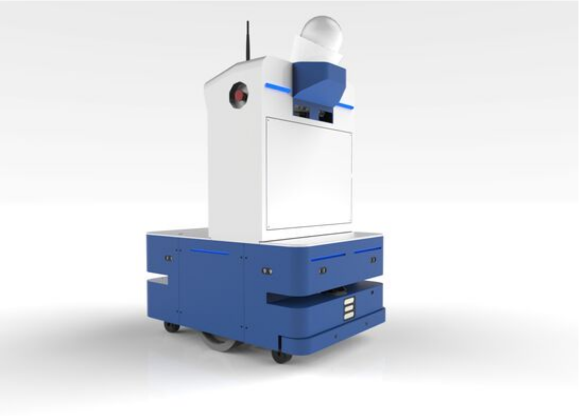
Auto Machine Series of Semiconductor

- ◆Loader & Unloader
- ◆Carrier Conversion Machine
- ◆Integrated System

Product line up

Auto Machine Series

MOBILE ROBOT



SECURITY ROBOT

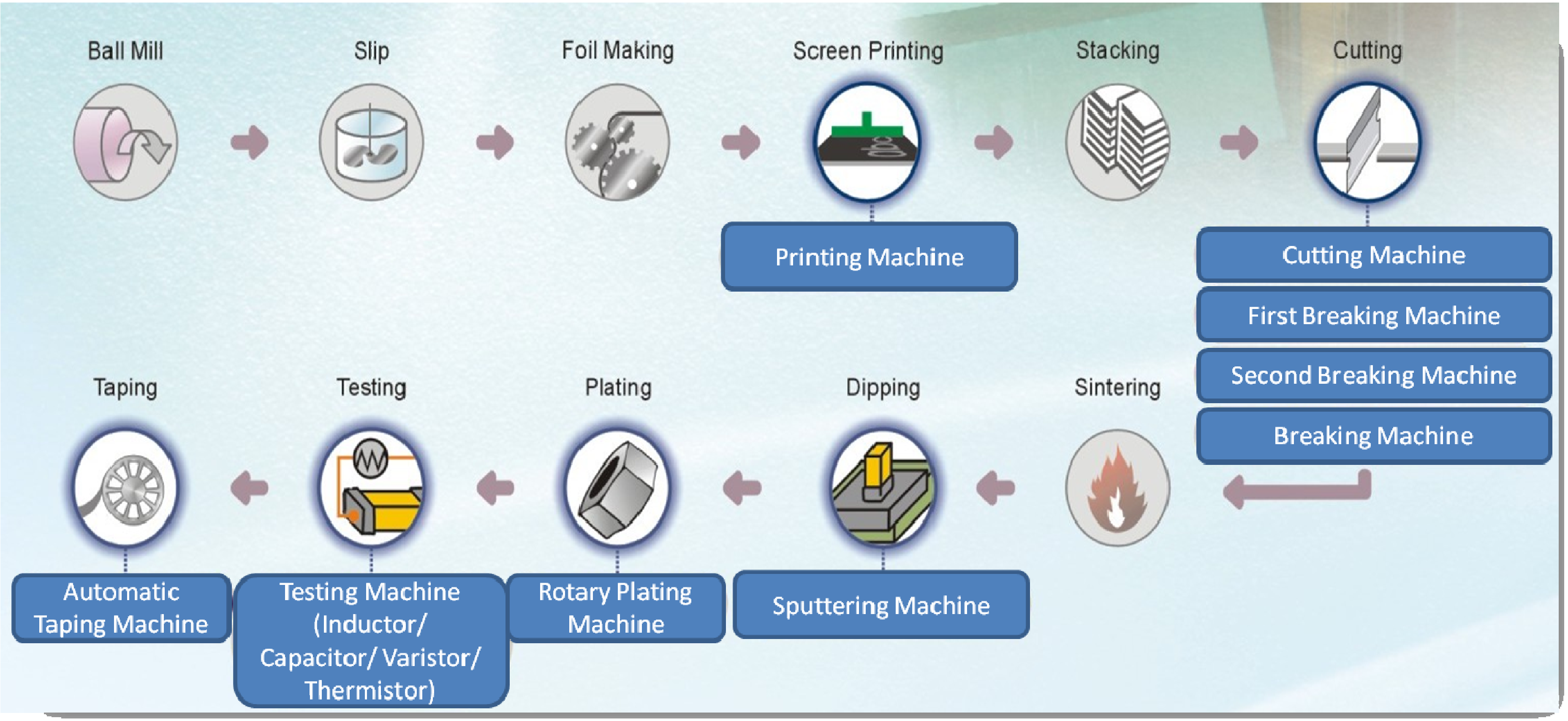
CLEANING ROBOT

Product line up

Passive Component

- ◆Rotary Plating Machine
- ◆R-Chip Taping Machine
- ◆Cutting Machine
- ◆Chip Resistor Breaking Machine
- ◆MLCI(High Frequency) Taping Machine (0.4*0.2mm chip)

Passive Component Production Process



Ball Mill → Slip → Foil Making → Screen Printing → Stacking → Cutting

Screen Printing: Printing Machine

Cutting:
- Cutting Machine
- First Breaking Machine
- Second Breaking Machine
- Breaking Machine

Sintering → Dipping → Plating → Testing → Taping

Dipping: Sputtering Machine

Plating: Rotary Plating Machine

Testing: Testing Machine (Inductor/ Capacitor/ Varistor/ Thermistor)

Taping: Automatic Taping Machine

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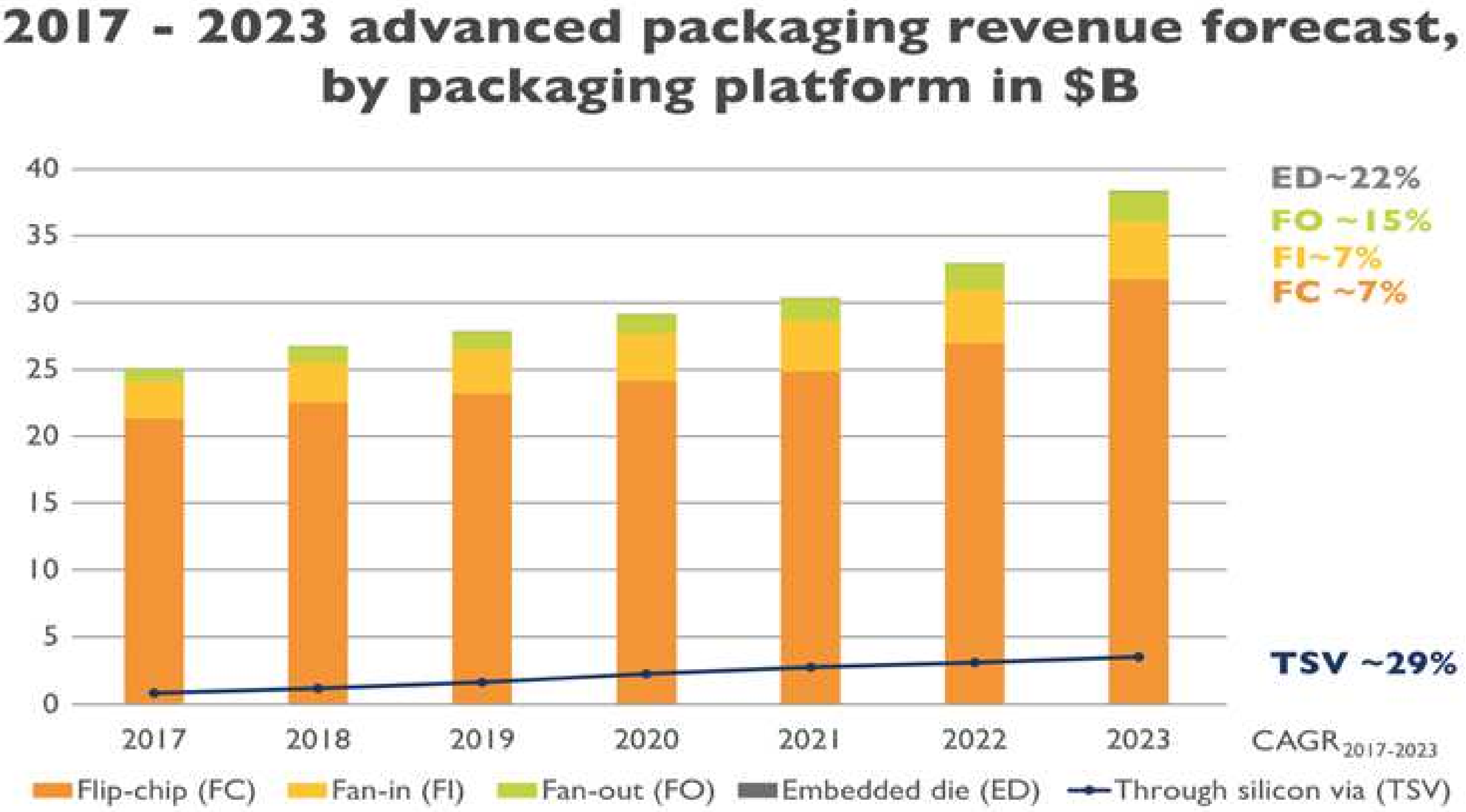
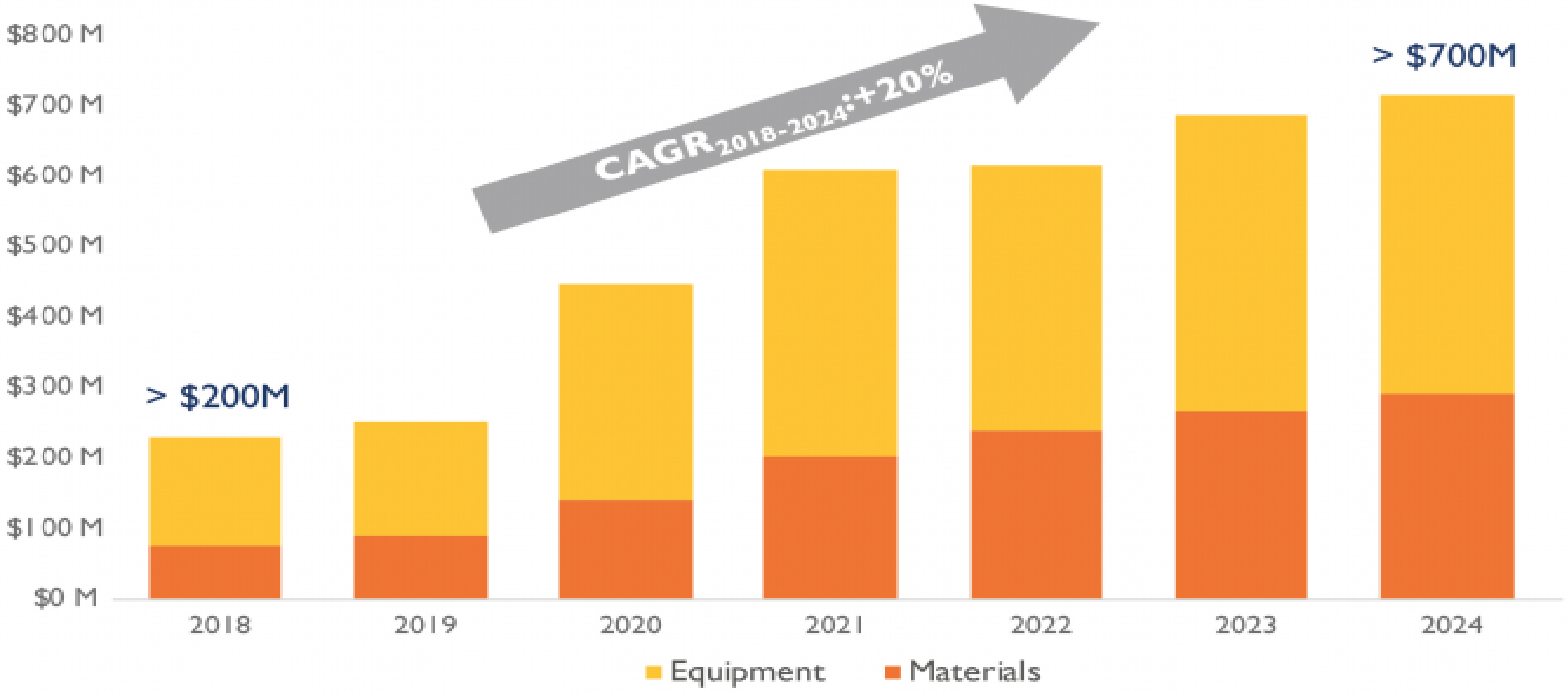
Industry Overview



出處: *(Source: Status of the Advanced Packaging Industry 2018 report, Yole Développement, September 2018)*

Industry Overview

Equipment and materials in Fan-Out packaging revenue forecast



出處: *(Source: Equipment and Materials for Fan-Out Packaging 2019 report, Yole Développement, 2019)*

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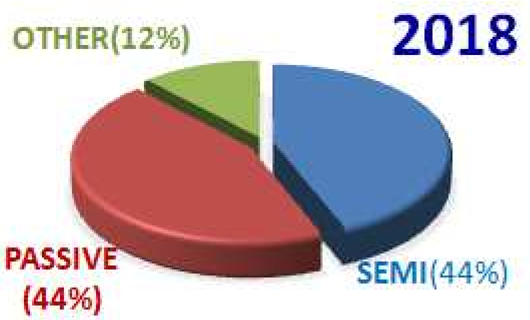
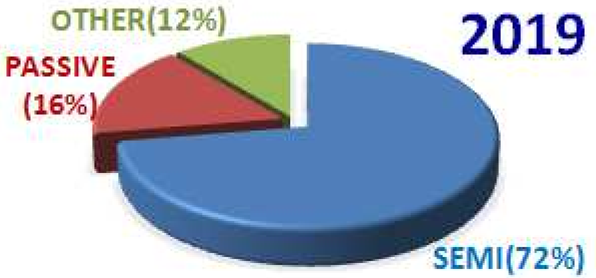
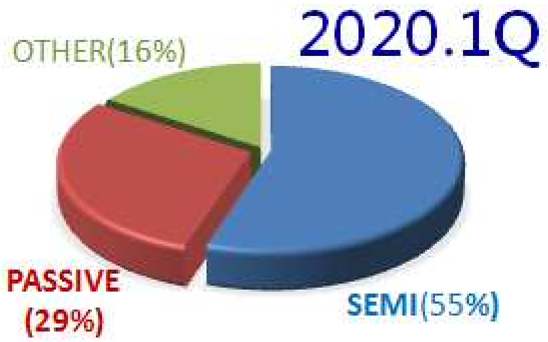
Revenue Breakdown

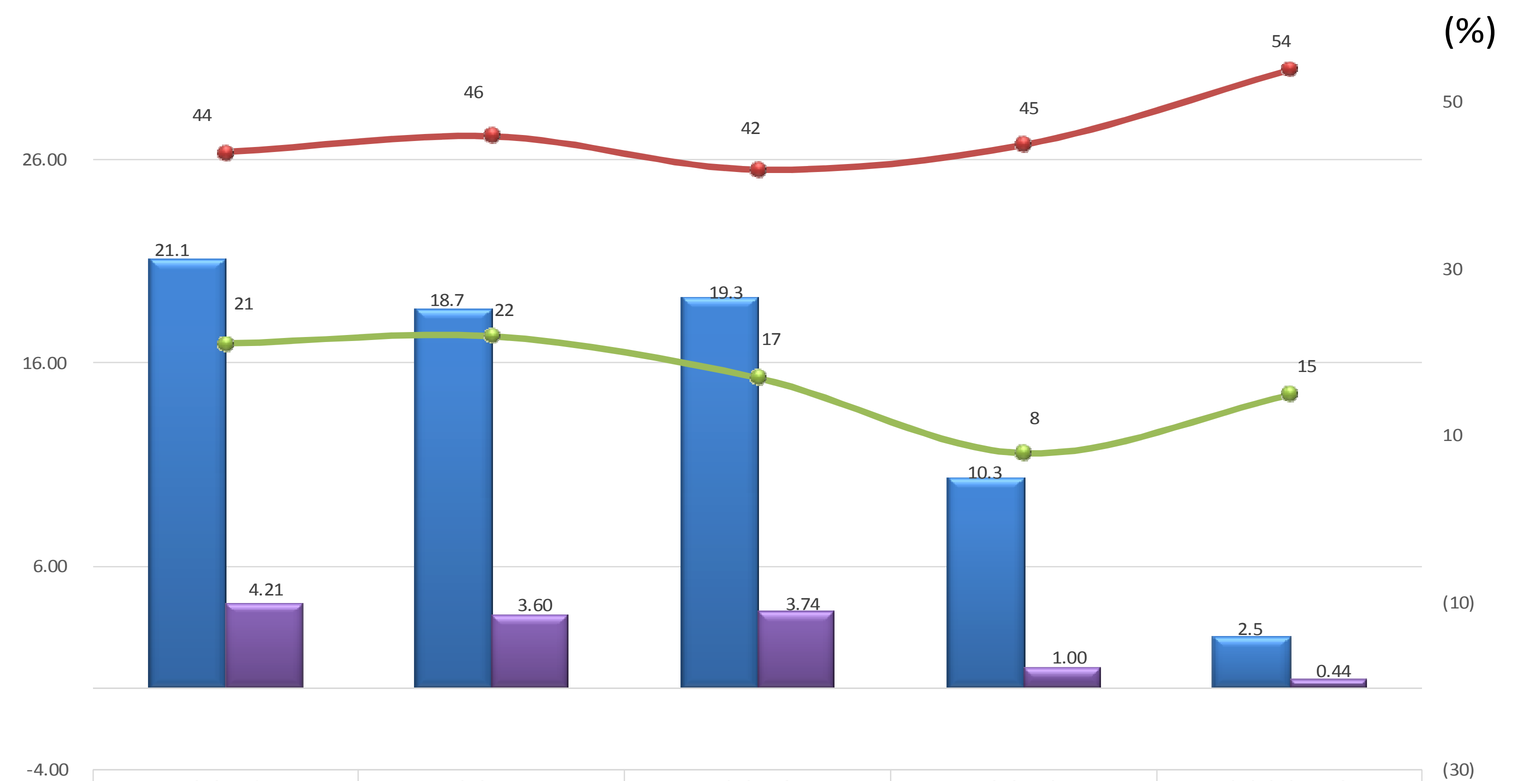






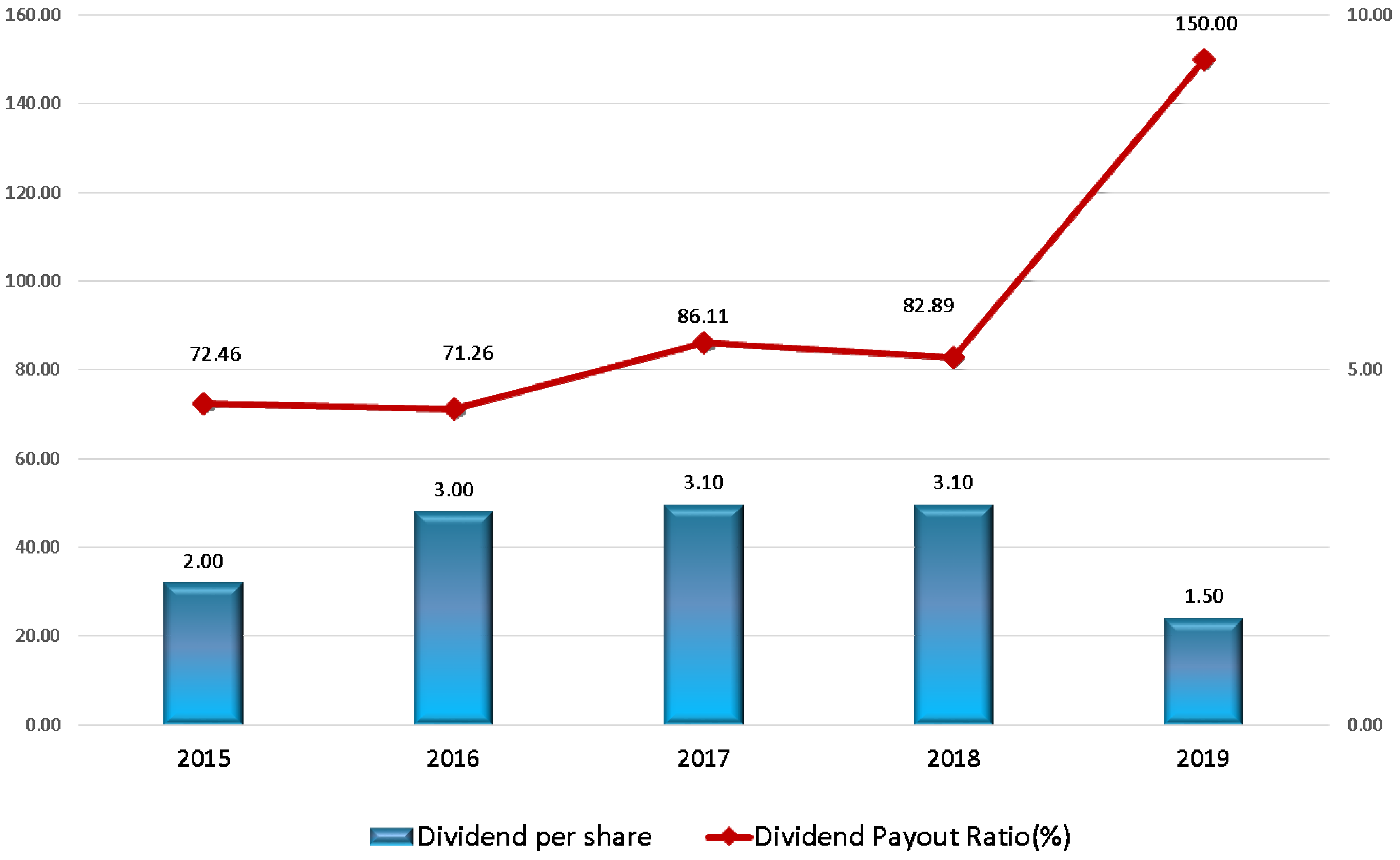
	2018	2019	2020.1Q
IC	8.46	7.48	1.40
PC	8.49	1.70	0.74
OTHER	2.31	1.14	0.40
TOTAL	19.26	10.32	2.54

Financial Highlights



	2016	2017	2018	2019	2020.1Q
▬ Sales(NT$100mn)	21.1	18.7	19.3	10.3	2.5
▬ EPS(NT$)	4.21	3.60	3.74	1.00	0.44
—●— GM(%)	44	46	42	45	54
—●— OPM(%)	21	22	17	8	15

Financial Highlights



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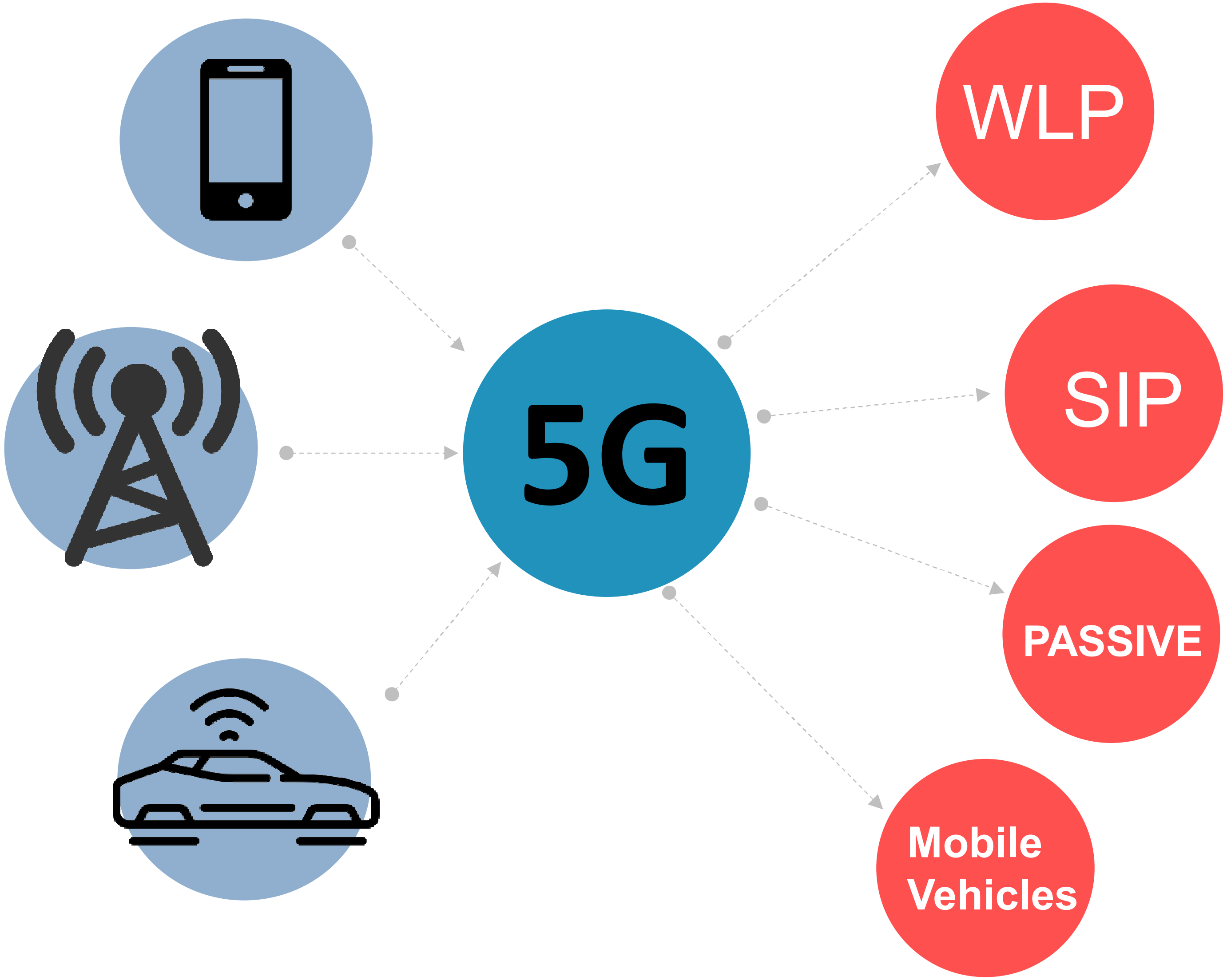
Future Prospects



Q & A

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